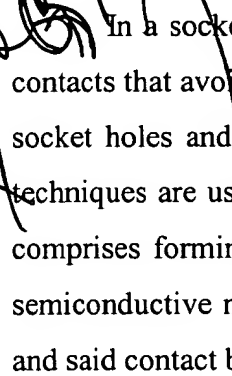


IN THE ABSTRACT:

Please amend the Abstract as follows:

 In a socket to test semiconductor die, a recessed socket contact and methods of making contacts that avoid pinching the die contacts are disclosed. [The socket contacts allow for smaller socket holes and allow denser contact spacing. In an embodiment, semiconductor fabrication techniques are used to construct a dense array of contacts.] A socket contact formation process comprises forming a contact head from a conductive material, forming a contact body from a semiconductive material configured to be electrically conductive; and joining said contact head and said contact body.